Supplier Name:	Texas Instruments Inc. (DUNS# 00-732-1904)
Contact Info:	ti.com/support
Form/Declaration Type:	Distribute - RoHS and IEC 62474 DB
Created on:	06/09/2022

Details for "TLV4316IDR"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TLV4316IDR	NIPDAU	Level-2-260C-1 YEAR	TI AGUASCALIENTES	D 14	8.7x3.9x1.75	151.3

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
Component				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Precious Metals	Gold	7440-57-5	0.211918	99.999528	999995	0.140038	1400
Precious Metals	Silver	7440-22-4	0.000001	0.000472	5	0.000001	0
Sub-Total			0.211919	100	1000000	0.140039	1400
Die Attach Adhesive	•	•	•				
Precious Metals	Silver	7440-22-4	0.232017	79.000109	790001	0.15332	1533
Thermoplastics	Ероху	85954-11-6	0.061675	20.999891	209999	0.040756	408
Sub-Total			0.293692	100	1000000	0.194076	1941
Lead Frame		·					
Copper and Its Alloys	Copper	7440-50-8	44.02932	97.41	974100	29.095178	290952
Copper and Its Alloys	Iron	7439-89-6	1.0848	2.4	24000	0.716851	7169
Copper and Its Alloys	Phosphorus	7723-14-0	0.01356	0.03	300	0.008961	90
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.01356	0.03	300	0.008961	90
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.01356	0.03	300	0.008961	90
Zinc and Its Alloys	Zinc	7440-66-6	0.0452	0.1	1000	0.029869	299
Sub-Total			45.2	100	1000000	29.86878	298688
Lead Frame Plating		· · · · · · · · · · · · · · · · · · ·					
Nickel and Its Alloys	Nickel	7440-02-0	0.644914	95.120059	951201	0.426168	4262
Precious Metals	Gold	7440-57-5	0.005288	0.779941	7799	0.003494	35
Precious Metals	Palladium	7440-05-3	0.027798	4.1	41000	0.018369	184
Sub-Total			0.678	100	1000000	0.448032	4480
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	91.411721	88	880000	60.406118	604061
Other Plastics and Rubber	Carbon Black	1333-86-4	0.311631	0.3	3000	0.20593	2059
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	0.571323	0.55	5500	0.377538	3775
Thermoplastics	Ероху	85954-11-6	11.582281	11.15	111500	7.65373	76537
Sub-Total			103.876956	100	1000000	68.643316	686433
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	1.068013	100	1000000	0.705758	7058
Sub-Total			1.068013	100	1000000	0.705758	7058
Total			151.32858			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm

for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**. See Glossary of Terms for more details.

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

For an explanation of the methods used to determine material weights, See Product Content Methodology

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

For additional information, please contact TI customer support.

Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo Created on: 06/09/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szzq088

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.